

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Huicai Zhong</td><td>05/18/2011</td></tr><tr><td>Qingqing Liang</td><td>05/18/2011</td></tr><tr><td>Haizhou Yin</td><td>05/18/2011</td></tr></tbody></table>	Name	Execution Date	Huicai Zhong	05/18/2011	Qingqing Liang	05/18/2011	Haizhou Yin	05/18/2011	
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Qingqing Liang	05/18/2011								
Haizhou Yin	05/18/2011								
RECEIVING PARTY DATA									
Name:	Institute of Microelectronics, Chinese Academy of Sciences								
Street Address:	No. 3 Beitucheng West Road								
Internal Address:	Chaoyang District								
City:	Beijing								
State/Country:	CHINA								
Postal Code:	100029								
PROPERTY NUMBERS Total: 1									
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>13132068</td></tr></tbody></table>	Property Type	Number	Application Number:	13132068					
Property Type	Number								
Application Number:	13132068								
CORRESPONDENCE DATA									
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ATTORNEY DOCKET NUMBER:	UNIT-01002US0								
NAME OF SUBMITTER:	Burt Magen								
Total Attachments: 2 source=1002-assignment#page1.tif source=1002-assignment#page2.tif									

CH \$40.00 13132068

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PATENT
REEL: 026365 FRAME: 0280

JOINT TO CORPORATE ASSIGNMENT

WHEREAS, the undersigned Inventors:

(1) Zhong, Huicai, a resident of Beijing, China;

(2) Liang, Qingqing, a resident of Beijing, China; and

(3) Yin, Haizhou, a resident of New York, United States of America.

have invented certain new and useful improvements in:

SHALLOW TRENCH ISOLATION STRUCTURE AND METHOD FOR FORMING THE SAME

and have executed a declaration for an application for a United States Patent disclosing and identifying the invention, the declaration being executed on May 18, 2011.

WHEREAS Institute of Microelectronics, Chinese Academy of Sciences, (hereinafter termed "Assignee"), a corporation, having a place of business at No. 3 Beitucheng West Road, Chaoyang District, Beijing 100029, China, wishes to acquire the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, certificates of invention and other forms of protection thereon (hereinafter termed "patents") applied for or granted in the United States and/or other countries.

NOW THEREFORE, for good and valuable consideration acknowledged by each of said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey to said Assignee, the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply in any or all countries of the world for patents, certificates of inventions or other governmental grants on said invention, including the right to apply for patents pursuant to the International Convention for the Protection of Industrial Property or pursuant to any other convention, treaty, agreement or understanding; (c) in and to any and all applications filed and any and all patents, certificates of inventions or other governmental grants granted on said invention in the United States or any other country, including each and every application filed and each and every patent granted on any application which is a division, substitution, or continuation of any of said applications; (d) in and to each and every reissue or extension of any of said patents; and (e) in and to each and every patent claim resulting from a reexamination certificate for any and all of said patents.

and to each and every patent claim resulting from a reexamination certificate for any and all of said patents.

2. Said Inventors hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and other countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, executing of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for complying with any duty of disclosure; (c) for prosecuting any of said applications; (d) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (e) for filing and prosecuting applications for reissue of any of said patents; (f) for interference or other priority proceedings involving said invention; and (g) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, reexamination proceedings, compulsory licensing proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.

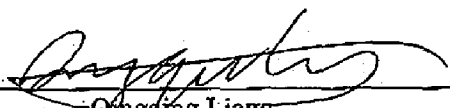
3. The terms and covenants of this Assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, their respective heirs, legal representatives and assigns.

4. Said Inventors hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

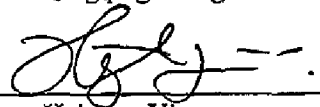
Date: 5/18/2011

(1) 
Huicai Zhong

Date: 5/18/2011

(2) 
Qingqing Liang

Date: 5/18/2011

(3) 
Haizhou Yin

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